

IN THE CLAIMS:

Please CANCEL claims 30-33 without prejudice or disclaimer.

Please AMEND claims 21-23 and 25-27, and ADD new claim 34, as follows. Note that all the claims currently pending in this application, including those not currently being amended, have been reproduced below for the Examiner's convenience.

1-20. (Cancelled)

21. (Currently Amended) A scan type exposure apparatus for transferring a pattern onto a substrate by scan exposure, said apparatus comprising:

a stage for moving the substrate in a Y direction corresponding to a scan direction, and in an X direction intersecting the scan direction;

an alignment scope for performing measurement for alignment of the substrate, at a position spaced, in the Y direction, from a position where the exposure of the substrate is to be carried out, said alignment scope being disposed on a straight line parallel to a Y-axis and passing through the position for exposure of the substrate;

an X measuring device for performing yaw measurement of said stage by use of an X reflection surface provided on said stage along the Y direction;

a Y measuring device for performing yaw measurement of said stage by use of a Y reflection surface provided on said stage along the X direction; and

a controller ~~being operable to select~~ which selects yaw measurement information of said X measuring device for an alignment operation including the alignment measurement using said alignment scope, and ~~being operable to select~~ which selects yaw measurement information of said Y measuring device for the scan exposure.

22. (Currently Amended) An apparatus according to Claim 21, wherein said X measuring device includes (i) an X-direction interferometer for measuring a position of said stage in the X direction and (ii) an X yaw interferometer cooperating with said X-direction interferometer to measure yawing of said stage, and said Y measuring device includes (i) a Y-direction interferometer for measuring a position of said stage in the Y direction and (ii) a Y yaw interferometer cooperating with said Y-direction interferometer ~~to~~ for measuring yawing of said stage.

23. (Currently Amended) An apparatus according to Claim 22, wherein said X-direction interferometer and said X yaw interferometer are arranged to use a light beam reflected by said X reflection surface, and said Y-direction interferometer and said Y yaw interferometer are arranged to use a light beam reflected by said X reflection surface.

24. (Previously Presented) An apparatus according to Claim 23, wherein, in the scan exposure, said controller performs position control of said stage, on the basis of said Y-direction interferometer, said Y yaw interferometer, and said X-direction interferometer.

25. (Currently Amended) An apparatus according to Claim 21, wherein said controller is operable, in accordance with an operation state of said exposure apparatus, including an alignment operation and a scan exposure operation, to perform performs an averaging processing or a statistical processing to yaw measurement data obtained by said X measuring device and said Y measuring device when an alignment operation and a scan exposure operation are not carried out.

26. (Currently Amended) An apparatus according to Claim 21, wherein said controller is operable to perform performs yaw measurement using said X measuring device, when said stage is to be moved after the alignment measurement using said alignment scope.

27. (Currently Amended) A scan type exposure apparatus for transferring a pattern onto a substrate by scan exposure, said apparatus comprising:

a stage for moving the substrate in a Y direction corresponding to a scan direction, and in an X direction intersecting the scan direction;

an alignment scope for performing measurement for alignment of the substrate, at a position spaced, in the X direction, from a position where the exposure of the substrate is to be carried out, said alignment scope being disposed on a straight line parallel to an X-axis and passing through the position for exposure of the substrate;

a Y measuring device for performing yaw measurement of said stage by use of a Y reflection surface provided on said stage along the X direction, said Y measuring device

including (i) a Y-direction interferometer for measuring a position of said stage in the Y direction, and (ii) a Y yaw interferometer being cooperable with said Y-direction interferometer to measure yawing of said stage; and

a controller ~~being operable to select~~ which selects yaw measurement information of said Y measuring device, both for an alignment measurement using said alignment scope and for the scan exposure operation.

28. (Previously Presented) An apparatus according to claim 27, further comprising an X measuring device for performing yaw measurement of said stage by use of an X reflection surface provided on said stage along the Y direction, wherein said X measuring device includes  
(i) an X-direction interferometer for measuring a position of said stage in the X direction and  
(ii) an X yaw interferometer being cooperable with said X-direction interferometer to measure yawing of said stage.

29. (Previously Presented) An apparatus according to Claim 28, wherein said X-direction interferometer and said X yaw interferometer are arranged to use a light beam reflected by said X reflection surface, and said Y-direction interferometer and said Y yaw interferometer are arranged to use a light beam reflected by said Y reflection surface.

30-33. (Cancelled)

34. (New) A device manufacturing method including:

a step of transferring a pattern onto a substrate by use of a scan type exposure apparatus that comprises (i) a stage for moving the substrate in a Y direction corresponding to a scan direction, and in an X direction intersecting the scan direction, (ii) an alignment scope for performing measurement for alignment of the substrate, at a position spaced, in the Y direction, from a position where the exposure of the substrate is to be carried out, the alignment scope being disposed on a straight line parallel to a Y-axis and passing through the position for exposure of the substrate, (iii) an X measuring device for performing yaw measurement of the stage by use of an X reflection surface provided on the stage along the Y direction, (iv) a Y measuring device for performing yaw measurement of the stage by use of a Y reflection surface provided on the stage along the X direction, and (v) a controller which selects yaw measurement information of the measuring device for an alignment operation including the alignment measurement using the alignment scope, and which selects yaw measurement information for the Y measuring device for the scan exposure.